

ProLight PM6N-TFXE 0.3W Power LED Technical Datasheet Version: 1.6

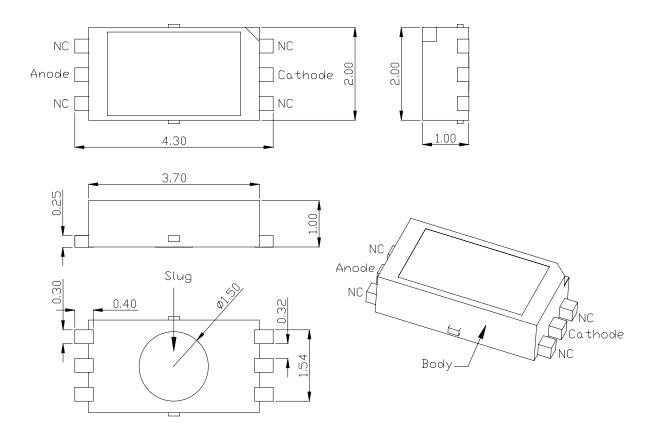
Features

- Very long operating life(up to 100k hours)
- Good color uniformity
- Industry best moisture sensitivity level JEDEC 2a
 4 week floor life without reconditioning
- Low-temp. & lead free reflow solder JEDEC 020d compatible (235°C)
- RoHS compliant
- More energy efficient than incandescent and most halogen lamps
- Low Voltage DC operated
- Instant light (less than 100ns)
- No UV

Typical Applications

- Reading lights (car, bus, aircraft)
- Portable (flashlight, bicycle)
- Uplighters/Downlighters
- Decorative/Entertainment
- Bollards/Security/Garden
- Cove/Undershelf/Task
- Indoor/Outdoor Commercial and Residential Architectural
- Automotive Ext (Stop-Tail-Turn, CHMSL, Mirror Side Repeat)
- LCD backlights

Emitter Mechanical Dimensions



Notes:

- 1. The cathode side of the device is denoted by the chamfer on the part body.
- 2. Electrical insulation between the case and the board is required --- slug of device is not electrically neutral. Do not electrically connect either the anode or cathode to the slug.
- 3. Drawing not to scale.
- 4. All dimensions are in millimeters.
- 5. All dimendions without tolerances are for reference only.
- 6. Please do not solder the emitter by manual hand soldering, otherwise it will damage the emitter.
- 7. Please do not use a force of over 3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.

^{*}The appearance and specifications of the product may be modified for improvement without notice.

Flux Characteristics at 80mA, $T_J = 25$ °C

0-1	Part Number	Lumious Flux Φ_{V} (lm)		
Color	Emitter	Minimum	Typical	
White	PM6N-TFWE	8.2	12.5	
Warm White	PM6N-TFVE	8.2	11.2	
Green	PM6N-TFGE	8.2	11.0	
Blue	PM6N-TFBE	1.0	1.3	
Amber	PM6N-TFAE	4.9	6.5	
Red	PM6N-TFRE	4.9	6.5	
	Warm White Green Blue Amber	White PM6N-TFWE Warm White PM6N-TFVE Green PM6N-TFGE Blue PM6N-TFBE Amber PM6N-TFAE	Color Emitter Minimum White PM6N-TFWE 8.2 Warm White PM6N-TFVE 8.2 Green PM6N-TFGE 8.2 Blue PM6N-TFBE 1.0 Amber PM6N-TFAE 4.9	

- ProLight maintains a tolerance of ± 10% on flux and power measurements.
- Please do not drive at rated current more than 1 second without proper heat sink.

Electrical Characteristics at 80mA, T_J = 25°C

	Forwa	rd Voltage	V _F (V)	Dynamic	Temperature Coefficient of V _F (mV/ °C)	Thermal Resistance Junction to
Color	Min.	Тур.	Max.	Resistance (Ω)	$\Delta V_F / \Delta T_J$	Slug (°C/W)
White	3.3	3.6	3.9	1.0	-2.0	10
Warm White	3.3	3.6	3.9	1.0	-2.0	10
Green	3.3	3.7	4.1	1.0	-2.0	10
Blue	3.3	3.6	3.9	1.0	-2.0	10
Amber	2.0	2.4	3.0	2.4	-2.0	10
Red	2.0	2.4	3.0	2.4	-2.0	10

Optical Characteristics at 80mA, $T_J = 25$ °C

Radiation	Color		nt Wavele Temperat	0	Spectral Half-width (nm) Δλ _{1/2}	Temperature Coefficient of Dominant Wavelength (nm/ °C) Δλ _D / ΔΤ _J	Total included Angle (degrees)	Viewing Angle (degrees) 2 θ _{1/2}
Pattern		IVIIII.	Тур.	IVIAX.	ΔΛ _{1/2}	ΔΛ _D / Δ1 _J	θ _{0.90V}	2 01/2
	White	4100 K	5500 K	10000 K			160	120
	Warm White	2700 K	3300 K	4100 K			160	120
Lambertian	Green	515 nm	525 nm	535 nm	35	0.04	160	120
Lambordan	Blue	455 nm	465 nm	475 nm	25	0.04	160	120
	Amber	587 nm	592 nm	597 nm	20	0.05	160	120
	Red	613.5 nm	623 nm	631 nm	20	0.05	160	120

 $[\]bullet$ ProLight maintains a tolerance of ± 5% for CCT measurements.

Absolute Maximum Ratings

Parameter	White/Warm White/ Green/Blue/Amber/Red	
DC Forward Current (mA)	80	
Peak Pulsed Forward Current (mA)	120	
Average Forward Current (mA)	80	
ESD Sensitivity	±500V HBM	
LED Junction Temperature (°C)	120	
Aluminum-core PCB Temperature (°C)	105	
Storage & Operating Temperature (°C)	-40 to +105	
Soldering Temperature(°C)	JEDEC 020d 235°C	

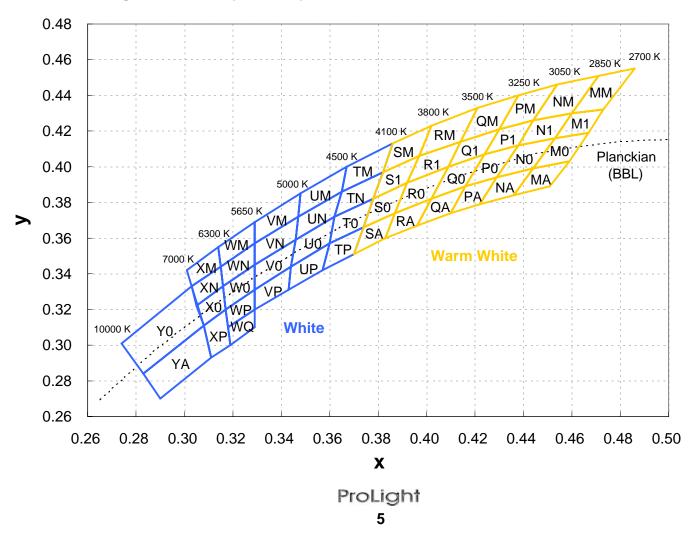
Photometric Luminous Flux Bin Structure

Color	Bin Code	Minimum Photometric Flux (Im)	Maximum Photometric Flux (Im)
	K	8.2	10.7
White	L	10.7	13.9
	M	13.9	18.1
	K	8.2	10.7
Warm White	L	10.7	13.9
	M	13.9	18.1
Green	K	8.2	10.7
Giccii	L	10.7	13.9
Blue	С	1.0	2.0
Amber	Н	4.9	6.3
Ambei	J	6.3	8.2
Reb	Н	4.9	6.3
- Keb	J	6.3	8.2

 $[\]bullet$ ProLight maintains a tolerance of \pm 10% on flux and power measurements.

Color Bin

White and Warm White Binning Structure Graphical Representation



Color Bins

White Bin Structure

T0	0.345 0.331 0.320 0.333 0.345 0.333 0.344 0.357	5970 5970
TN 0.362 0.372 0.316 0.316 0.382 0.378 0.382 4300 WN 0.316 0.316 0.316 0.316 0.316 0.316 0.316 0.316 0.316 0.316 0.316 0.316 0.315 0	0.320 0.333 0.345 0.333 0.344 0.357	
0.360 0.357 0.317 (0.317 0.362 0.372 0.316 (0.382 0.397 0.329 (0.378 0.362 0.372 4300 WN 0.315 (0.365 0.365 0.386 0.329 (0.329 0.329 (0.329 0.329 0.329 (0.329 0.329 0.329 0.329 (0.329 0.329 0.329 0.329 (0.329 0.329 0.329 0.329 (0.329 0.329 0.329 0.329 (0.329 0.329 0.329 0.329 0.329 (0.329 0.329 0.329 0.329 0.329 (0.329 0.329 0.329 0.329 0.329 (0.329 0.329 0.329 0.329 0.329 (0.329 0.329 0.329 0.329 0.329 0.329 (0.329 0.329	0.333 0.345 0.333 0.344 0.357 0.331	
0.382 0.397 0.329 0 TN 0.378 0.382 4300 WN 0.316 0 0.362 0.372 0.315 0 0.365 0.386 0.329 0	0.345 0.333 0.344 0.357 0.331	5970
TN 0.378 0.382 4300 WN 0.316 0 0.362 0.372 4300 WN 0.315 0 0.365 0.386 0.329 0	0.333 0.344 0.357 0.331	5970
0.362 0.372 4300 WN 0.315 (0.365 0.386 0.329 (0.344 0.357 0.331	5970
0.365 0.386 0.329	0.357 0.331	
	0.331	
0.374 0.366 0.329 0		
	0.320	5970
	0.310 0.320	
	0.320	
	0.310 0.300	5970
	0.300 0.310	
	0.369	
	0.357 0.344	5970
	0.3 44 0.355	
	0.311	
	0.322 0.333	6650
	0.320	
	0.320 0.322	
0.257 0.242 0.202 0.202	0.333	
).333).344	6650
	0.333	
	0.311	
0.267 0.400 0.217 (0.320	
	0.300	6650
	0.293	
	0.342	
0.320 0.345 0.314 (0.355	
	0.344	6650
	0.333	
	0.311	
0.220 0.257 0.292 (0.284	
	0.301	8000
	0.333	
	0.311	
0.244 0.244 0.214 0.214	0.293	0000
	0.270	8000
	0.284	
0.329 0.357		
0.320 0.360		
VM 0.329 0.369 5320 0.348 0.385		
0.347 0.372		

 $[\]bullet$ Tolerance on each color bin (x , y) is \pm 0.01

Color Bins

Warm White Bin Structure

Bin Code	x	у	Typ. CCT (K)	Bin Code	x	у	Typ. CCT (K)
	0.453	0.416			0.409	0.400	
MO	0.444	0.399	2770	Q0	0.402	0.382	3370
IVIO	0.459	0.403	2110	Qυ	0.416	0.389	3370
	0.467	0.419			0.424	0.407	
	0.460	0.430			0.414	0.414	
M1	0.453	0.416	2770	Q1	0.409	0.400	3370
	0.467	0.419	2170	α.	0.424	0.407	0070
	0.473	0.432			0.430	0.421	
	0.459	0.403			0.416	0.389	
MA	0.444	0.399	2770	QA	0.402	0.382	3370
1717 (0.436	0.384	2170	Q, t	0.396	0.367	0070
	0.451	0.389			0.410	0.374	
	0.471	0.451			0.421	0.433	
MM	0.460	0.430	2770	QM	0.414	0.414	3370
	0.473	0.432	2170	QIVI	0.430	0.421	0070
	0.486	0.455			0.438	0.440	
	0.438	0.412			0.392	0.391	
N0	0.429	0.394	2950	R0	0.387	0.374	3650
110	0.444	0.399	2000	110	0.402	0.382	0000
	0.453	0.416			0.409	0.400	
	0.444	0.426			0.414	0.414	
N1	0.438	0.412	2950	R1	0.409	0.400	3650
141	0.453	0.416	2500	17.1	0.392	0.391	0000
	0.460	0.430			0.397	0.406	
	0.444	0.399			0.387	0.374	
NA	0.429	0.394	2950	RA	0.383	0.360	3650
14/ (0.422	0.379	2500	100	0.396	0.367	0000
	0.436	0.384			0.402	0.382	
	0.454	0.446			0.421	0.433	
NM	0.444	0.426	2950	RM	0.414	0.414	3650
I VIVI	0.460	0.430	2500	IXIVI	0.397	0.406	0000
	0.471	0.451			0.402	0.423	
	0.424	0.407			0.392	0.391	
P0	0.416	0.389	3150	S0	0.387	0.374	3950
1 0	0.429	0.394	0100	00	0.374	0.366	0000
	0.438	0.412			0.378	0.382	
	0.430	0.421			0.397	0.406	
P1	0.424	0.407	3150	S1	0.392	0.391	3950
	0.438	0.412	3130	01	0.378	0.382	3330
	0.444	0.426			0.382	0.397	
	0.429	0.394			0.382 0.387	0.374	
PA	0.416	0.389	3150	SA	0.383	0.360	3950
1 🔿	0.410	0.374	3130	υ Λ	0.370	0.351	3330
	0.422	0.379			0.374	0.366	
	0.438	0.440			0.402	0.423	
PM	0.430	0.421	3150	SM	0.397	0.406	3950
E IVI	0.444	0.426	3100	SIVI	0.382	0.397	3930
	0.454	0.446			0.386	0.413	

 $[\]bullet$ Tolerance on each color bin (x , y) is \pm 0.01

Dominant Wavelength Bin Structure

Color	Bin Code	Minimum Dominant Wavelength (nm)	Maximum Dominant Wavelength (nm)
	А	515	520
Green	1	520	525
Orcon	2	525	530
	3	530	535
	А	455	460
Blue	1	460	465
Dide	2	465	470
	3	470	475
	2	587.0	589.5
Amber	4	589.5	592.0
ATTIOCI	6	592.0	594.5
	7	594.5	597.0
Pod	2	613.5	620.5
Red	4	620.5	631.0

 $[\]bullet$ ProLight maintains a tolerance of \pm 1nm for dominant wavelength measurements.

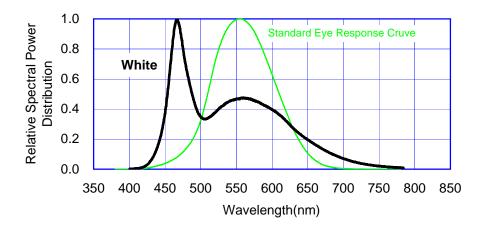
Forward Voltage Bin Structure

Color	Bin Code	Minimum Voltage (V)	Maximum Voltage (V)
	Α	3.3	3.5
White	В	3.5	3.7
	С	3.7	3.9
	Α	3.3	3.5
Warm White	В	3.5	3.7
	С	3.7	3.9
	Α	3.3	3.5
Green	В	3.5	3.7
Green	С	3.7	3.9
	D	3.9	4.1
	Α	3.3	3.5
Blue	В	3.5	3.7
	С	3.7	3.9
	Α	2.0	2.2
	В	2.2	2.4
Amber	С	2.4	2.6
	D	2.6	2.8
	E	2.8	3.0
	Α	2.0	2.2
	В	2.2	2.4
Red	С	2.4	2.6
	D	2.6	2.8
	E	2.8	3.0

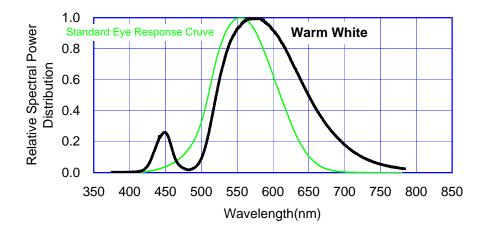
[•] ProLight maintains a tolerance of ± 0.1 for Voltage measurements.

Color Spectrum, T_J = 25°C

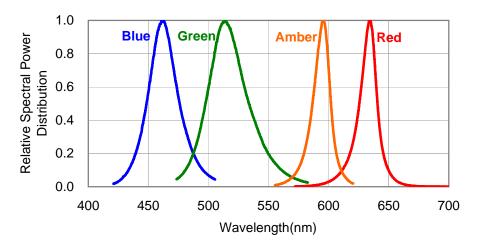
1. White



2. Warm White



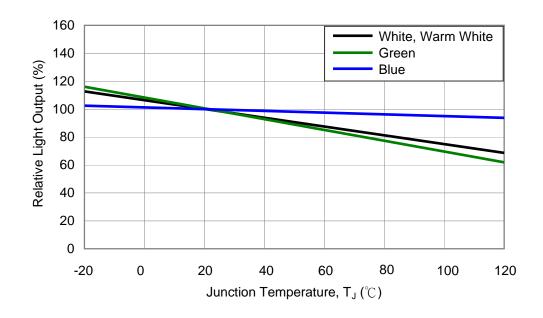
3. Blue · Green · Amber · Red

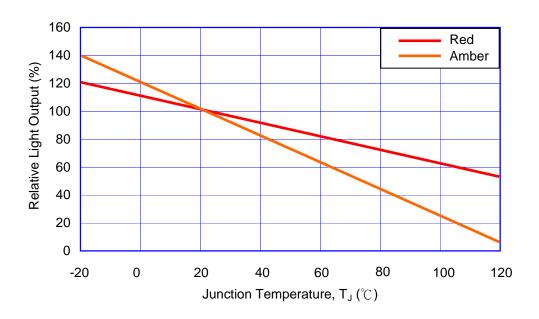


ProLight 10

Light Output Characteristics

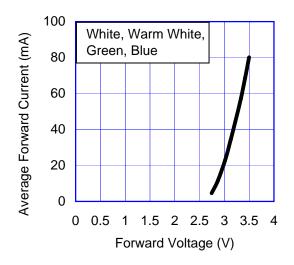
Relative Light Output vs. Junction Temperature at 80mA

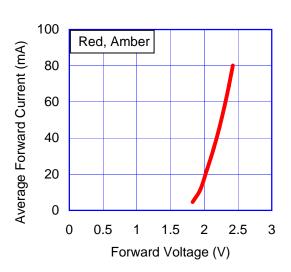




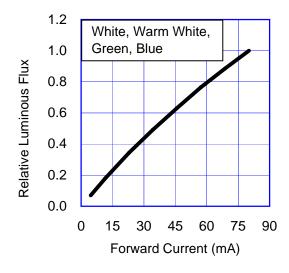
Forward Current Characteristics, $T_J = 25$ °C

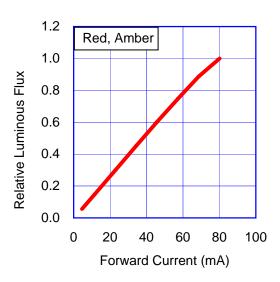
1. Forward Voltage vs. Forward Current





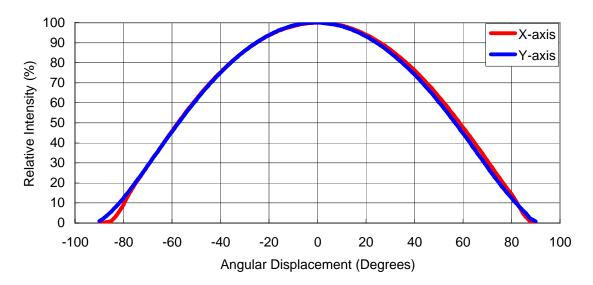
2. Forward Current vs. Normalized Relative Luminous Flux





Typical Representative Spatial Radiation Pattern

Lambertian Radiation Pattern



Moisture Sensitivity Level - JEDEC 2a

			Soak Requirements			
Level	Floor Life		Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
22	4 wooks	≤30°C /	696 +5/-0	30°C /	120 +1/-0	60°C /
2a 4 weeks	4 WEEKS	60% RH	090 +5/-0	60% RH	120 +1/-0	60% RH

- The standard soak time includes a default value of 24 hours for semiconductor manufature's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.
- Table below presents the moisture sensitivity level definitions per IPC/JEDEC's J-STD-020C.

			Soak Requirements			
Level	Floor Life		Stan	dard	Accelerated Environment	
	Time Conditions Time (hours) Condition		Conditions	Time (hours)	Conditions	
1	Unlimited	≤30°C /	168 +5/-0	85°C /	NA	NA
		85% RH	100 101 0	85% RH		
2	1 year	≤30°C /	168 +5/-0	85°C /	NA	NA
	i yeai	60% RH	100 +5/-0	60% RH	INA	INA
2a	4 weeks	≤30°C /	696 +5/-0	30°C /	120 +1/-0	60°C /
Za	4 Weeks	60% RH	090 +5/-0	60% RH	120 +1/-0	60% RH
3	168 hours	≤30°C /	192 +5/-0	30°C /	40 +1/-0	60°C /
	100 110013	60% RH	192 +3/-0	60% RH	40 +1/-0	60% RH
4	72 hours	≤30°C /	96 +2/-0	30°C /	20 +0.5/-0	60°C /
	72 Hours	60% RH	90 + 2/-0	60% RH	20 +0.5/-0	60% RH
5	48 hours	≤30°C /	72 +2/-0	30°C /	15 +0.5/-0	60°C /
5	40 Hours	60% RH	1 Z +2/-0	60% RH	15 +0.5/-0	60% RH
5a	24 hours	≤30°C /	48 +2/-0	30°C /	10 +0.5/-0	60°C /
Ja	24 Hours	60% RH	40 +2/-0	60% RH	10 +0.5/-0	60% RH
6	Time on Label	≤30°C /	Time on Label	30°C /	NA	NA
U	(TOL)	60% RH	(TOL)	60% RH	INA	INA

Qualification Reliability Testing

Stress Test	Stress Conditions	Stress Duration	Failure Criteria	
Room Temperature	25°C, I _F = max DC (Note 1)	1000 hours	Note 2	
Operating Life (RTOL)		1000 110010	11010 2	
Wet High Temperature	85°C/60%RH, I _F = max DC (Note 1)	1000 hours	Note 2	
Operating Life (WHTOL)		1000 110010	11010 2	
Wet High Temperature	85°C/85%RH, non-operating	1000 hours	Note 2	
Storage Life (WHTSL)	oo o/oo/oran, non operating	1000 110013	14010 2	
High Temperature	110°C, non-operating	1000 hours	Note 2	
Storage Life (HTSL)	110 O, Horr operating	1000 110013	14010 2	
Low Temperature	-40°C, non-operating	1000 hours	Note 2	
Storage Life (LTSL)	40 O, non operating	1000 110013	14010 2	
Non-operating	-40°C to 120°C, 30 min. dwell,	200 cycles	Note 2	
Temperature Cycle (TMCL)	<5 min. transfer	200 0y0103		
Non-operating	-40°C to 120°C, 20 min. dwell,	200 cycles	Note 2	
Thermal Shock (TMSK)	<20 sec. transfer	200 cycles	14010 2	
Mechanical Shock	1500 G, 0.5 msec. pulse,		Note 3	
Wiconamoar Chock	5 shocks each 6 axis		14010 0	
Natural Drop	On concrete from 1.2 m, 3X		Note 3	
Variable Vibration	10-2000-10 Hz, log or linear sweep rate,		Note 3	
Frequency	20 G about 1 min., 1.5 mm, 3X/axis		Note 3	
Solder Heat Resistance (SHR)	260°C ± 5°C, 10 sec.		Note 3	
Coldorability	Steam age for 16 hrs., then solder dip		Solder coverage	
Solderability	at 260°C for 5 sec.		on lead	

Notes:

1. Depending on the maximum derating curve.

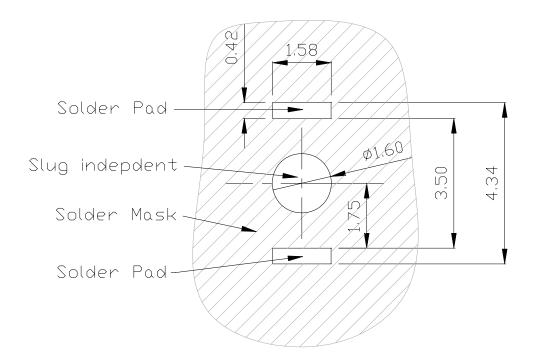
2. Criteria for judging failure

Item	Test Condition	Criteria for Judgement	
		Min.	Max.
Forward Voltage (V _F)	I _F = max DC	-	Initial Level x 1.1
Luminous Flux or Radiometric Power (Φ_V)	I _F = max DC	Initial Level x 0.7	-
Reverse Current (I _R)	$V_R = 5V$	-	50 μA

^{*} The test is performed after the LED is cooled down to the room temperature.

3. A failure is an LED that is open or shorted.

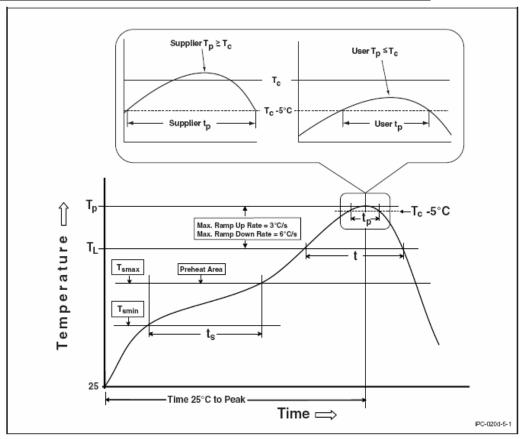
Recommended Solder Pad Design



- All dimensions are in millimeters.
- Electrical isolation is required between Slug and Solder Pad.

Reflow Soldering Condition - IPC/JEDEC J-STD-020d

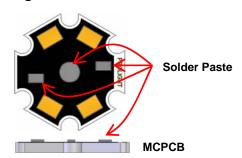
Profile Feature	Low-Temp. & Pb-Free Assembly (Bi-Sn Eutectic Assembly)	
Preheat & Soak		
Temperature min (T _{smin})	100 °C	
Temperature max (T _{smax})	150 °C	
Time (T _{smin} to T _{smax})	60-120 seconds	
Average Ramp-Up Rate (T _{smax} to T _P)	3 °C / second max.	
Liquidous temperature (T _L)	183°C	
Time at liquidous (t _L)	60-150 seconds	
Peak package body temperature (T _P)	235°C	
Time (t _P) within 5°C of the specified	20 seconds	
classification temperature (T _C)		
Average ramp-down rate (T _P to T _{smax})	6 °C/second max.	
Time 25°C to Peak Temperature	6 minutes max.	



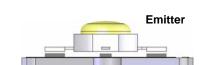
- All temperatures refer to topside of the package, measured on the package body surface.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

Heat Plate Soldering Condition

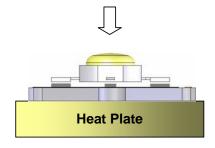
(1) Soldering Process for Solder Paste



Use Solder Mask to print Solder Paste on MCPCB.



Place Emitter on MCPCB.

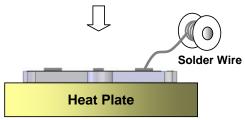


Put MCPCB on Heat Plate until Solder Paste melt. The Solder Paste sould be melted within 10 seconds. Take out MCPCB out from Heat Plate within 15 seconds.

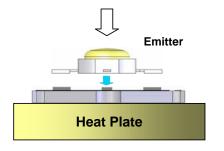
(2) Soldering Process for Solder Wire



Put MCPCB on Heat Plate.



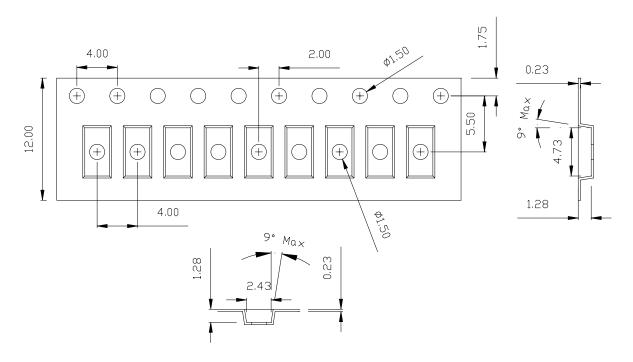
Place Solder Wire to the solder pad of MCPCB.

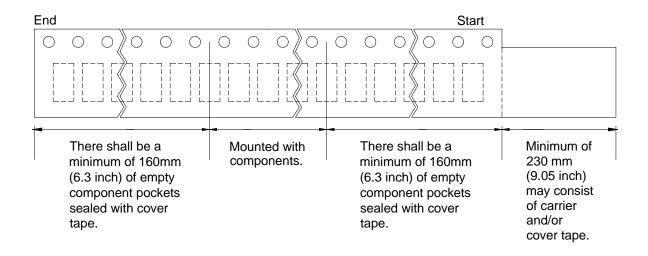


Put Emitter on MCPCB. Take the MCPCB out from Heat Plate within 10 seconds.

- \bullet Heat plate temperature: 230°C max for Lead Solder and 260°C max for Lead-Free Solder.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

Emitter Reel Packaging

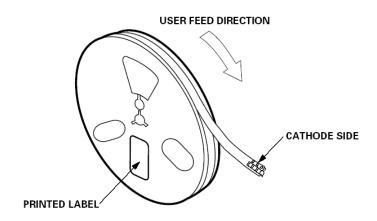


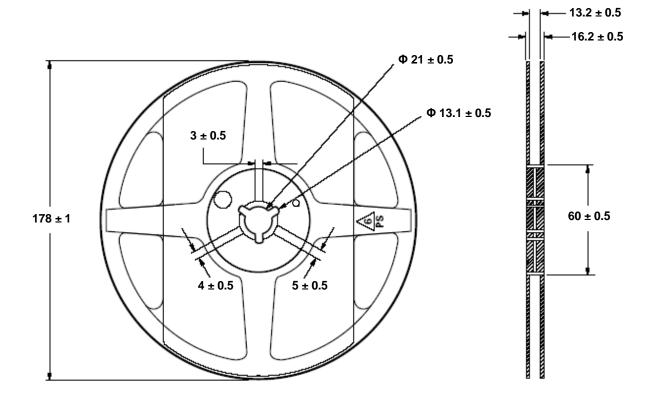


Notes:

- 1. Drawing not to scale.
- 2. All dimensions are in millimeters.
- 3. General tolerance is \pm 0.10 mm.

Emitter Reel Packaging





Notes:

- 1. Empty component pockets sealed with top cover tape.
- 2. 250~2000 pieces per reel.
- 3. Drawing not to scale.
- 4. All dimensions are in millimeters.

Precaution for Use

Storage

Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing ProLight's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH. It is also recommended to return the LEDs to the MBB and to reseal the MBB.

- The slug is is not electrically neutral. Therefore, we recommend to isolate the heat sink.
- The slug is to be soldered. If not, please use the heat conductive adhesive.
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- Please avoid rapid cooling after soldering.
- Components should not be mounted on warped direction of PCB.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When cleaning is required, isopropyl alcohol should be used.
- When the LEDs are illuminating, operating current should be decide after considering the package maximum temperature.
- The appearance and specifications of the product may be modified for improvement without notice.

Handling of Silicone Lens LEDs

Notes for handling of silicone lens LEDs

- Please do not use a force of over 3kgf impact or pressure on the silicone lens, otherwise it will cause a catastrophic failure.
- The LEDs should only be picked up by making contact with the sides of the LED body.
- Avoid touching the silicone lens especially by sharp tools such as Tweezers.
- Avoid leaving fingerprints on the silicone lens.
- Please store the LEDs away from dusty areas or seal the product against dust.
- When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the silicone lens must be prevented.
- Please do not mold over the silicone lens with another resin. (epoxy, urethane, etc)

